



## TECHNICAL DATA SHEET

### **Sn95Cu4Ag1 Solder Bar**

Lead Free



#### Description

**Kurtel Sn95Cu4Ag1** Solder Bar guarantees that lead free application can be produced according to **RoHS II** (2011/65/EU). This high-melting alloy contains CuSn and AgSn intermetallic compounds, therefore its mechanical properties are pleasing to the users. The specific density of lead-free solder alloys will be lower compared to leaded alloys. Due to low density, the spent solder weight will be less than leaded alloys.

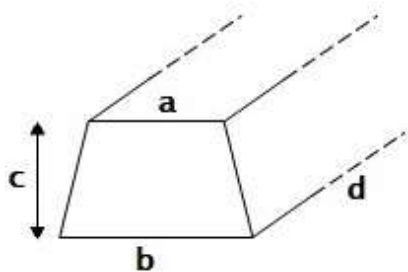
Advantages;

- RoHS II
- Fast wetting
- The effects of intermetallic compounds on mechanical properties
- Lower density than leaded alloys.

#### Physical Properties & Product Forms

Properties	Sn95Cu4Ag1
Solder Composition:	Sn %95 ( $\pm 0,15$ ) Ag %1 ( $\pm 0,15$ ) Cu %4 ( $\pm 0,15$ )
Melting Point:	217 °C Solidus 353 °C Liquidus
Specific Gravity:	7,4 g/cm <sup>3</sup>

**Kurtel Sn95Cu4Ag1 solder bar** is trapezoidal 0,95 kg ingot form in 20kg box packages.



#### Dimensions

a : 20 mm  
b : 24 mm  
c : 17 mm  
d : 350 mm



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#### **Storage & Shelf Life**

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Dry at room temperature. Solder has an indefinite shelf life.

#### **Health & Safety**

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Before using please read the MSDS.